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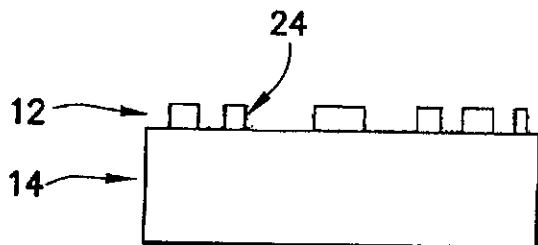
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(54) Title: PH BUFFERED COMPOSITIONS FOR CLEANING SEMICONDUCTOR SUBSTRATES



(57) Abstract: A semi-aqueous cleaning formulation use-
ful for removing particles from semiconductor wafer sub-
strates formed during a dry etching process for semiconduc-
tor devices, the cleaning formulation comprising a buffering
system a polar organic solvent, and a fluoride source.

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